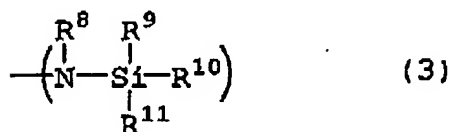
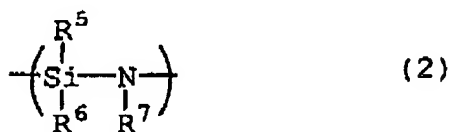


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Complete set of Claims

[1] (currently amended) A coating composition comprising: a polyalkylsilazane compound; an acetoxysilane compound; and an organic solvent; where said polyalkylsilazane compound contains one or both groups represented by formulae (2) and (3)



wherein R⁵ to R¹¹ each independently represent a hydrogen atom or an alkyl group having 1 to 3 carbon atoms, provided that both R⁵ and R⁶ do not simultaneously represent hydrogen and all of R⁹ to R¹¹ do not simultaneously represent hydrogen, and further where the acetoxysilane compound is selected from tetraacetoxysilane, methyltriacetoxysilane, ethyltriacetoxysilane, ethoxytriacetoxysilane, isopropoxytriacetoxysilane, n-butoxytriacetoxysilane, dimethyldiacetoxysilane, diethyldiacetoxysilane, diisopropyldiacetoxysilane, di-n-butyldiacetoxysilane, dimethoxydiacetoxysilane, diethoxyacetoxysilane, diisopropoxydiacetoxysilane, and di-n-butoxydiacetoxysilane.

[2] (original) The coating composition according to claim 1, which further comprises a pore forming agent.

[3] (currently amended) The coating composition according to claim 2, wherein said pore forming agent is ~~a copolymer comprising~~ a siloxy-containing polyethylene

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oxide compound or a siloxy-containing polyethylene oxide compound as monomer units.

[4] (cancel)

[5] (withdrawn) A siliceous material produced by coating a coating composition according to claim 1 onto a substrate or by filling a coating composition according to any one of claims 1 to 4 into a frame or a groove, and firing the coating composition.

[6] (withdrawn) A semiconductor device comprising a siliceous material according to claim 5 as an intermetal dielectric.

[7] (withdrawn) A process for producing a siliceous material, comprising heating a coating composition according to claim 1 at a temperature of 350°C or below for 1 to 60 min.

[8] (cancel).

[9] (cancel).

[10] (new) The coating composition according to claim 1, further where the acetoxysilane compound is in the range 5% to 40% by weight of based on the weight of the polyalkylsilazane compound.